

L Number	Hits	Search Text	DB	Time stamp
1	775	(plasma adj treatment)with silicon	USPAT; US-PGPUB	2004/01/20 10:28
2	0	(plasma adj treatment)with (silicon adj tip)	USPAT; US-PGPUB	2004/01/20 10:28
3	0	(plasma adj treatment)with (emitter adj tip)	USPAT; US-PGPUB	2004/01/20 10:29
4	839	nitridation with nitrogen	USPAT; US-PGPUB	2004/01/20 10:49
5	0	nitridation with nitrogen with plasma with tip	USPAT; US-PGPUB	2004/01/20 10:50
6	12	nitrogen with plasma with tip	USPAT; US-PGPUB	2004/01/20 11:38
7	3180	(313/309-311,351,336).CCLS.	USPAT; US-PGPUB	2004/01/20 11:40
-	28	((plasma adj enhanced adj chemical adj vapor adj deposition)PECVD)with hydrogenation	USPAT; US-PGPUB	2004/01/16 11:06
-	677	((plasma adj enhanced adj chemical adj vapor adj deposition)PECVD)with (oxygen)	USPAT; US-PGPUB	2004/01/15 10:46
-	39	((plasma adj enhanced adj chemical adj vapor adj deposition)PECVD)near hydrogen	USPAT; US-PGPUB	2004/01/15 10:50
-	0	((plasma adj enhanced adj chemical adj vapor adj deposition)PECVD)near hydrogen with (reduce near oxygen)	USPAT; US-PGPUB	2004/01/15 10:50
-	0	((plasma adj enhanced adj chemical adj vapor adj deposition)PECVD)near hydrogen with (reduced near oxygen)	USPAT; US-PGPUB	2004/01/15 10:51
-	3	((plasma adj enhanced adj chemical adj vapor adj deposition)PECVD)near hydrogen with (oxygen)	USPAT; US-PGPUB	2004/01/15 10:52
-	6	((plasma adj enhanced adj chemical adj vapor adj deposition)PECVD)near hydrogen with (oxide)	USPAT; US-PGPUB	2004/01/15 11:02
-	0	(field adj emitter adsj tip)with oxide with (reduced less) and((plasma adj enhanced adj chemical adj vapor adj deposition)PECVD)near hydrogen	USPAT; US-PGPUB	2004/01/15 11:03
-	0	(field adj emitter adj tip)with oxide with (reduced less) and((plasma adj enhanced adj chemical adj vapor adj deposition)PECVD)near hydrogen	USPAT; US-PGPUB	2004/01/15 11:04
-	0	(field adj emitter adj tip)with oxide with (reduced less)	USPAT; US-PGPUB	2004/01/15 11:04
-	14	(field adj emitter adj tip)with oxide	USPAT; US-PGPUB	2004/01/15 11:32
-	1	("5747384").PN.	USPAT; US-PGPUB	2004/01/15 11:55
-	1	("5853492").PN.	USPAT; US-PGPUB	2004/01/15 12:01
-	1541	(313/495-497).CCLS.	USPAT; US-PGPUB	2004/01/15 13:31
-	8	("4125446" "4792842" "5147819" "5229331" "5358908" "5372973" "5923953" "6154188").PN.	USPAT	2004/01/15 12:25
-	10	("5038070" "5188977" "5319233" "5319279" "5541473" "5644156" "5659224" "5723867" "5796211" "5834790").PN.	USPAT	2004/01/15 12:33
-	2	("4804253" "5126620").PN.	USPAT	2004/01/15 12:41
-	18	("3665241" "3921022" "3970887" "3998678" "4008412" "4095133" "4163949" "4307507" "4513308" "4578614" "4818914" "4964946" "4990766" "5012153" "5030895" "5053673" "5142184" "5164632").PN.	USPAT	2004/01/15 13:17
-	1	"4008412".PN.	USPAT	2004/01/15 13:24
-	1	("4728851").PN.	USPAT; US-PGPUB	2004/01/15 13:46
-	20	5371431.URPN.	USPAT	2004/01/15 13:33
-	1	("6136621").PN.	USPAT; US-PGPUB	2004/01/15 14:13

-	14	("4964946" "5151061" "5186670" "5188977" "5229331" "5371431" "5378182" "5466982" "5481156" "5504385" "5514847" "5529524" "5548181" "5739628").PN.	USPAT	2004/01/15 13:46
-	1	("5371431").PN.	USPAT; US-PGPUB	2004/01/15 17:09
-	18	("3665241" "3921022" "3970887" "3998678" "4008412" "4095133" "4163949" "4307507" "4513308" "4578614" "4818914" "4964946" "4990766" "5012153" "5030895" "5053673" "5142184" "5164632").PN.	USPAT	2004/01/15 14:14
-	20	5371431.URPN.	USPAT	2004/01/15 14:16
-	8	kanicki-.in.	USPAT; US-PGPUB; EPO; JPO; DERWENT	2004/01/15 17:11
-	1	(kanicki-.in.)and barrier	USPAT; US-PGPUB; EPO; JPO; DERWENT	2004/01/15 17:13
-	34	(glass adj substrate)with (barrier adj film)	USPAT; US-PGPUB	2004/01/16 17:17
-	2	pecvd adj hydrogenation adj process	USPAT; US-PGPUB	2004/01/16 11:07
-	3216	hydrogenation adj process	USPAT; US-PGPUB	2004/01/16 11:08
-	264	(hydrogenation adj process).ti.	USPAT; US-PGPUB	2004/01/16 11:12
-	0	(emitter adj tip)with hydrogenation	USPAT	2004/01/16 11:13
-	87	(emitter adj tip)with oxide	USPAT	2004/01/16 12:02
-	1	("5186670").PN.	USPAT; US-PGPUB	2004/01/16 12:44
-	1	("6086442").PN.	USPAT; US-PGPUB	2004/01/16 13:38
-	1	("5853492").PN.	USPAT; US-PGPUB	2004/01/16 15:39
-	1	("5089292").PN.	USPAT; US-PGPUB	2004/01/16 15:44
-	1	("5371431").PN.	USPAT; US-PGPUB	2004/01/16 15:48
-	0	(field adj emission)and (silicon adj grid) and (metal adj grid)and (passivation adj layer)	USPAT	2004/01/16 15:50
-	0	(field adj emission)and (grid) and (metal adj grid)and (passivation adj layer)	USPAT	2004/01/16 15:50
-	74	(field adj emission)and (grid) and metal and (passivation adj layer)	USPAT	2004/01/16 16:37
-	50	("3500102" "3814968" "3883760" "3970887" "4575765" "4859304" "4874981" "4940916" "4992137" "5000208" "5024722" "5049520" "5100355" "5141461" "5151061" "5162704" "5186670" "5191217" "5199917" "5204581" "5205770" "5210472" "5212426" "5219310" "5229331" "5229682" "5232549" "5259799" "5283500" "5329207" "5342477" "5358599" "5358601" "5358908" "5372973" "5374868" "5391259" "5448133" "5451830" "5483118" "5500750" "5620832" "5621272" "5632664" "5633560" "5637023" "5643033" "5643817" "5648698" "5648699").PN.	USPAT	2004/01/16 16:06
-	27	(field adj emission)and ((passivation adj layer)with nitride)	USPAT	2004/01/16 16:45
-	4266	passivation with nitride	USPAT	2004/01/16 17:06
-	40	Kanicki and substrate and chemical	USPAT; EPO; JPO; DERWENT	2004/01/16 17:10

-	155	substrate and (barrier adj (film layer)) and (field adj emission)	USPAT	2004/01/16 17:12
-	11	(glass adj substrate) with (barrier adj (film layer)) and (field adj emission)	USPAT	2004/01/16 17:13
-	23	(glass adj substrate)with (barrier adj film)	USPAT	2004/01/16 17:17
-	204	(313/495).CCLS.	US-PGPUB	2004/01/20 09:11
-	8	Raina-k\$.in.	US-PGPUB	2004/01/20 10:26